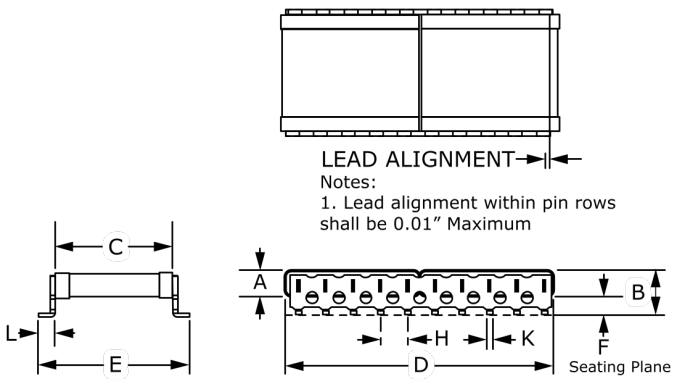
L1GL30G403KA02

KPS-MCC Indust C0G HT200C, Ceramic, 0.04 uF, 10%, 2000 VDC, C0G



Click here for the 3D model.

Dimensions

D	25.64mm +/-0.635mm
L	1.4mm +/-0.127mm
H	2.54mm NOM
F	1.778mm +/-0.25mm
A	2.79mm MAX
B	4.822mm MAX
C	11.43mm +/-0.635mm
E	13.7mm +/-0.89mm
K	0.5mm NOM

Packaging Specifications

Packaging	Waffle, Box
Packaging Quantity	16

General Information

Series	KPS-MCC Indust C0G HT200C
Style	Leaded Stacked Chip
Description	Low ESR, Stacked Ceramic Chips
Features	200C, Low ESR, High Thermal Stability, Bulk Capacitance
RoHS	With Exemptions
REACH	SVHC (Pb – CAS 7439-92-1)
SCIP Number	297427bb-2a48-4853-b594-641304a2cc24
Termination	Silver
Lead	L Leads
AEC-Q200	No
Notes	Number of chips in this stack: 2.

Specifications

Capacitance	0.04 uF
Capacitance Tolerance	10%
Voltage DC	2000 VDC
Dielectric Withstanding Voltage	2400 VDC
Temperature Range	-55/+200°C
Temperature Coefficient	C0G
Dissipation Factor	0.1% 1 kHz 25C
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	25 GOhms